

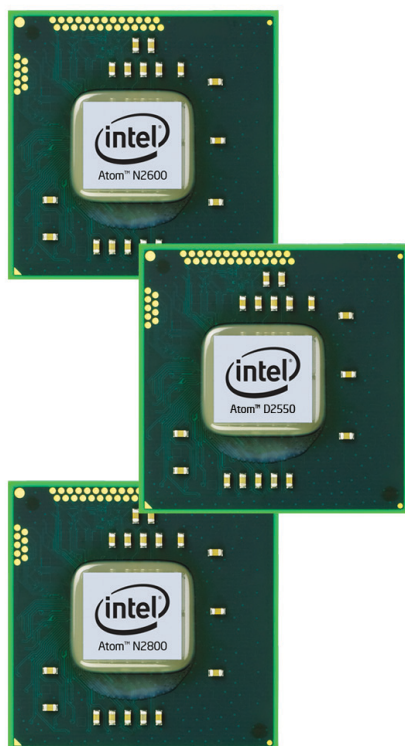
PLATFORM BRIEF

Intel® Atom™ Processor N2000 and D2000 Series with Intel® NM10 Express Chipset
Intelligent Systems



Intel® Atom™ Processor N2000 and D2000 Series-Based Platforms for Intelligent Systems

Ideal for Intelligent Systems—context-aware, securely managed embedded devices that connect seamlessly to networks, clouds and each other.



Overview

The Intel® Atom™ processor N2000 and D2000 series feature new levels of performance-per-watt, opening the door to always-on, always-connected, intelligent, embedded devices. Based on 32nm process technology, they offer significant power-reduction and performance improvements to deliver the best-in-class response time of any embedded Intel® Atom™ processor. The series offer a range of thermal design power¹ (TDP) from 3.5 W to 10 W for power-efficient, fanless embedded designs, with stunning video graphics performance and support for up to 4 GB of DDR3 system memory. Processors include:

- Intel® Atom™ processor N2600^A
- Intel® Atom™ processor N2800^A
- Intel® Atom™ processor D2550^A

These processors are paired with the Intel® NM10 Express chipset, providing rich I/O capabilities and flexibility via high-bandwidth interfaces such as PCI Express,* Serial ATA, Hi-Speed USB 2.0 connectivity and Intel® High Definition Audio.²

These platforms offer excellent solutions for embedded market segments such as digital signage, interactive clients (kiosks, point-of-sale terminals), thin clients, medical devices and industrial control. Processors are drop-in compatible, enabling platforms to scale seamlessly with minimal design effort. Additionally, they remain software compatible with previous 32-bit Intel® architecture and complementary silicon.

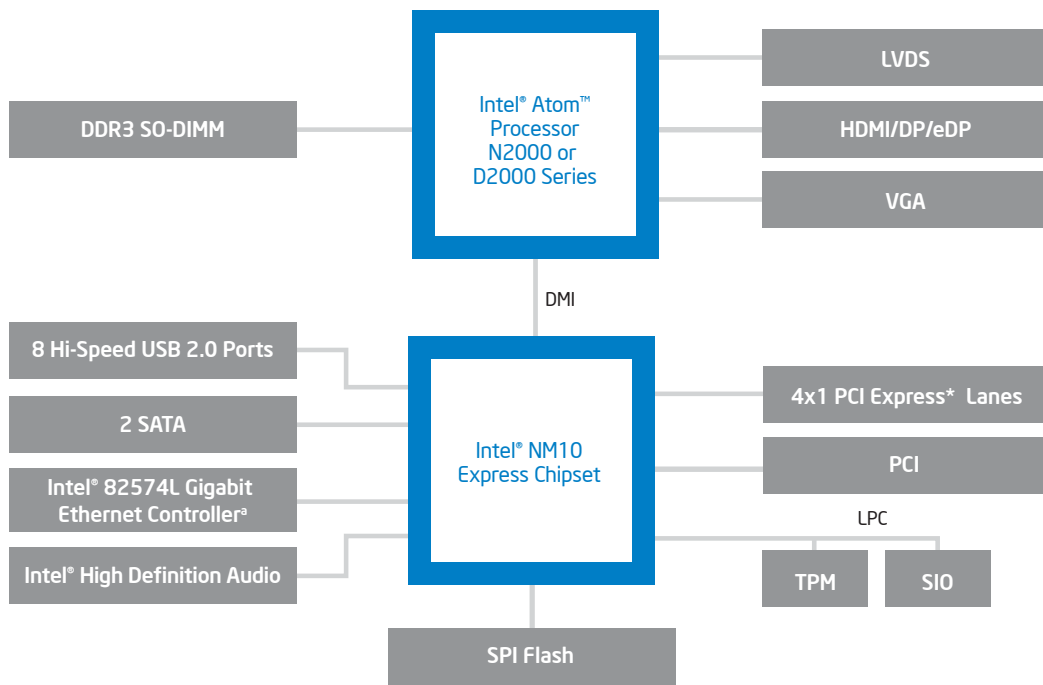
Product Highlights

- This series introduces the first embedded Intel Atom processor core based on Intel® 32nm logic technology, incorporating 2nd generation Hi-k metal gate transistors. The ultra-low power core includes low-standby/always-on circuit applications and high-voltage I/O transistors, enabling embedded computing devices to be more energy efficient, smaller in size, and offer more robust capabilities.
- Intel® Rapid Start Technology provides fast resume; Intel® Smart Connect Technology enables an always-updated experience even during standby.
- Integrated Intel® Graphics Media Accelerator 3600/3650 combined with the integrated memory controller provides enhanced performance and system responsiveness.
- Integrated hardware-accelerated decoder enables smooth full HD (up to 1080p) video playback and streaming at a fraction of the power consumption of previous generations.
- eDP/DP, LVDS, VGA and HDMI provide a wide range of display outputs for design flexibility and display scalability.
- Intel® Deep Power Down Technology significantly reduces power usage during idle periods so that internal transistor power leakage is minimal (available on N2600 and N2800).

- Intel® Hyper-Threading Technology³ (two threads) provides high-performance-per-watt efficiency in an in-order pipeline for increased system responsiveness in multi-tasking environments. One execution core is seen as two logical processors, and parallel threads are executed on a single core with shared resources.

- Intel® Streaming SIMD Extensions (SSE) 2 and Intel® SSE3 enable software to accelerate data processing in specific areas, such as complex arithmetic and video decoding.
- Execute Disable Bit⁴ prevents certain classes of malicious buffer overflow attacks.

- Along with a strong ecosystem of hardware and software vendors, including members of the Intel® Embedded Alliance (intel.com/go/eca), Intel helps to cost-effectively meet development challenges and speed time-to-market.
- Intel® Boot Loader Development Kit (Intel® BLDK) support helps optimize firmware to reduce boot time, firmware size and cost.⁵



^aThis device requires an x1 PCIe lane. Other Ethernet solutions from Intel include:
 – Intel® 82574IT Gigabit Ethernet Controller
 – Intel® 82583V Gigabit Ethernet Controller

Software Overview

The following independent operating system and BIOS vendors provide support for this platform:

OPERATING SYSTEM	CONTACT	BIOS
Microsoft Windows* 7	Intel provides drivers ⁵	American Megatrends
Microsoft Windows Embedded Standard 7	Intel provides drivers ⁵	Insyde Software
Microsoft Windows XP ⁵	Intel provides drivers ⁵	Phoenix Technologies
Microsoft Windows XPe ⁵	Intel provides drivers ⁵	Byosoft
Microsoft Windows Embedded CE 7.0 ⁵	Intel provides drivers ⁵	
MeeGo* 1.2	Intel provides drivers ⁵	
Yocto Project*	Intel provides drivers ⁵	
Wind River VxWorks* ⁵	Wind River	

Intel® Atom™ Processors for Intelligent Systems

Product Name ^Δ	Product Number	Cores	Core Speed	L2 Cache	Graphics Speed	C-States Supported	Thermal Design Power ¹	Tjunction	Package
Intel® Atom™ Processor N2600	DF8064101050706	2	1.60 GHz	1 MB (512 kB per core)	400 MHz	C0 – C6	3.5 W	0 to 90°C	437-ball lead-free FCBGA 22 mm x 22 mm
Intel® Atom™ Processor N2800	DF8064101050503	2	1.86 GHz	1 MB (512 kB per core)	640 MHz	C0 – C6	6.5 W	0 to 90°C	437-ball lead-free FCBGA 22 mm x 22 mm
Intel® Atom™ Processor D2550	DF8064101211300	2	1.86 GHz	1 MB (512 kB per core)	640 MHz	C0 – C1	10 W	0 to 90°C	437-ball lead-free FCBGA 22 mm x 22 mm

Intel® NM10 Express Chipset for Intelligent Systems

Product Name	Product Code	Thermal Design Power	Package	Features
Intel® NM10 Express Chipset	CG82NM10	1.5 W	360 MMAP 17 mm x 17 mm	4 PCI Express,* Serial ATA, Hi-Speed USB 2.0 connectivity, Intel® High Definition Audio interface ²

Intel in Embedded and Communications: intel.com/embedded

⁰Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. Go to: http://www.intel.com/products/processor_number for details.

¹The TDP specification should be used to design the processor thermal solution. TDP is not the maximum theoretical power the processor can generate.

²Requires an Intel® HD Audio enabled system. Consult your PC manufacturer for more information. Sound quality will depend on equipment and actual implementation. For more information about Intel® HD Audio, refer to <http://www.intel.com/design/chipsets/hdaudio.htm>.

³Requires an Intel® HT Technology enabled system, check with your PC manufacturer. Performance will vary depending on the specific hardware and software used. Not available on Intel® Core™ i5-750. For more information including details on which processors support HT Technology, visit <http://www.intel.com/info/hyperthreading>.

⁴Requires an Execute Disable Bit enabled system. Check with your PC manufacturer to determine whether your system delivers this functionality. For more information, visit <http://www.intel.com/technology/xdbit/index.htm>.

⁵Support for these operating systems and software ingredients will be available in Q1 of 2012.

⁶Drivers available at: downloadcenter.intel.com (enter chipset name).

Performance results are based on certain tests measured on specific computer systems. Any difference in system hardware, software or configuration will affect actual performance. Configurations: [describe config + what test used + who did testing]. For more information go to <http://www.intel.com/performance>.

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